



Patent Application Number: 10/006,966

Attorney Docket Number: Analog.5721-4

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

APPLICANT: Timothy R. SPOONER et al.

GROUP: 2829

SERIAL NO: 10/006,966

EXAMINER: S. Geyer

FILED: December 5, 2001

FOR: A METHOD AND DEVICE FOR PROTECTING MICRO
ELECTROMECHANICAL SYSTEMS STRUCTURES DURING
DICING OF A WAFER

Assistant Commissioner of Patents
Washington, D.C. 20231

Sir:

AMENDMENT UNDER 37 C.F.R. 1.111

In response to the Office Action mailed August 6, 2002, the following amendments and remarks are respectfully submitted under 37 C.F.R. 1.111 in connection with the above-identified application.

In the Specification

Please amend the following pages:

Page 16

Line 23, change "adhesive layer 10" to --adhesive layer 103--

Page 20

Line 13, after "dies" insert --200--

Page 23

Line 23, change "transfer tape 160" to -- transfer tape 190--

Line 25, change "transfer tape 160" to -- transfer tape 190--

In the Claims

Please amend the following claims:

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TECHNOLOGY CENTER 2800
OCT 11 2001
P. Geyer/H.
F. Walker
10-16-02